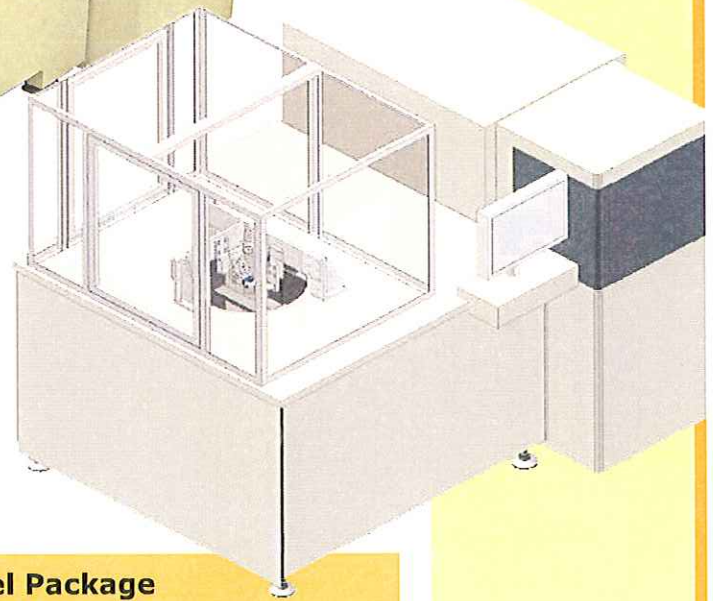
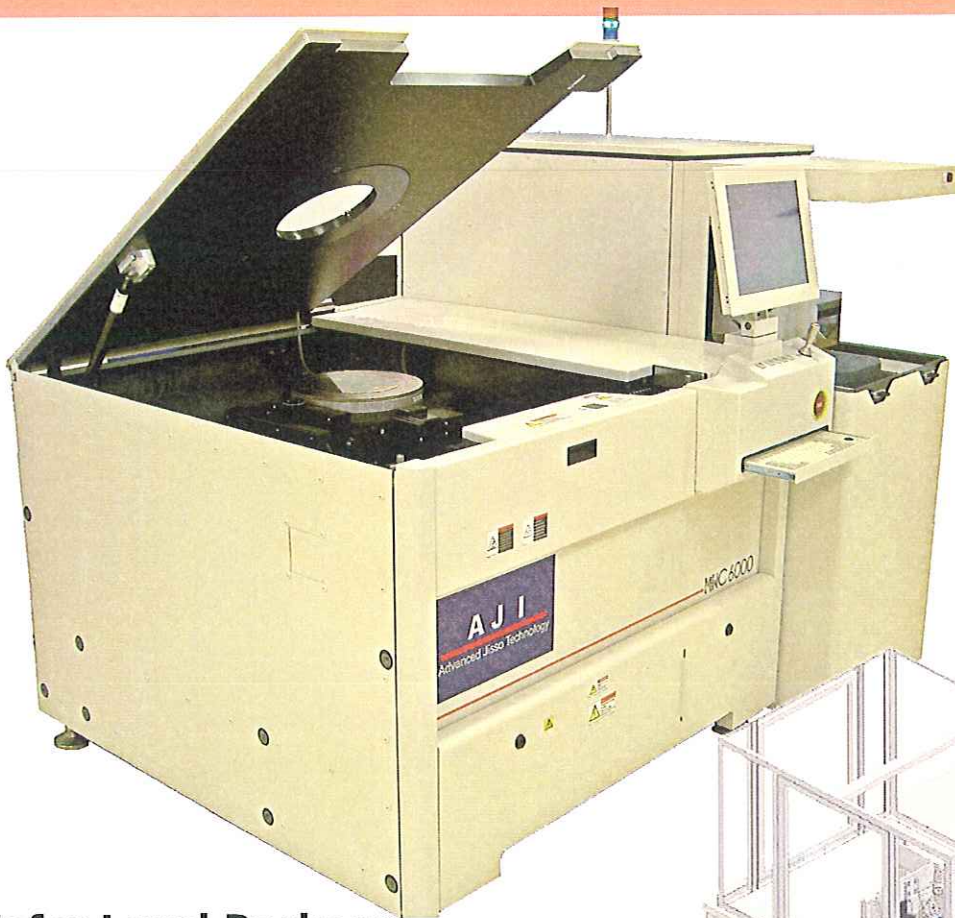


Wafer Level Package Micro WorkCell Series

MWC6000



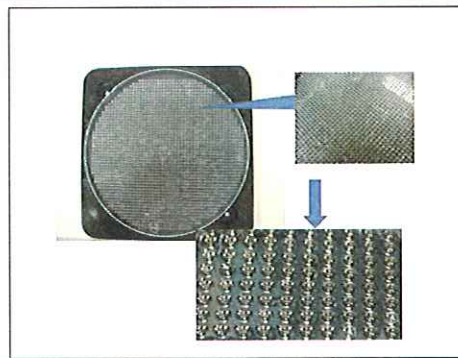
Wafer Level Package

- Process for Chip Bonder, Chip Sorter
- Wafer size 100mm-300mm

Applications

- Wafer Level Mold
- Wafer Level Bonder
- Wafer Level Inspection
- Dispensing
- Flip Chip Bonding
- Singulation
- Chip Stacking
- Chip Sorting
- Chip on Wafer

Wafer Level Package



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